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ON Semiconductor®

## IRF644B

# **N-Channel BFET MOSFET 250 V, 14 A, 280 m**Ω

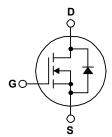
### Description

These N-Channel enhancement mode power field effect transistors are produced using ON Semiconductor's proprietary, planar, DMOS technology. This advanced technology has been especially tailored to minimize onprovide superior resistance, switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters and switch mode power supplies.

### **Features**

- 14 A, 250 V,  $R_{DS(on)}$  = 280 m $\Omega$  @  $V_{GS}$  = 10 V
- Low gate charge (Typ. 47 nC)
- Low Crss (Typ. 30 pF)
- · Fast Switching
- 100% Avalanche Tested
- · Improved dv/dt Capability





# **Absolute Maximum Ratings** T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter		IRF644B_FP001	Unit
V <sub>DSS</sub>	Drain-Source Voltage		250	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C	C)	14	Α
	- Continuous (T <sub>C</sub> = 100°	°C)	8.9	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	56	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	480	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	14	А
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	13.9	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.8	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> = 25°C)		139	W
	- Derate Above 25°C		1.11	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	ge	-55 to +150	°C
T <sub>L</sub>	Maximum Lead Temperature for Soldering 1/8" from Case for 5 Seconds	g,	300	°C

### **Thermal Characteristics**

Symbol	Parameter	IRF644B-FP001	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.9	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	°C/W

# **Package Marking and Ordering Information**

-	Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
	IRF644B-FP001	IRF644B	TO-220	Tube	N/A	N/A	50 units

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	250			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.24		V/°C
I <sub>DSS</sub>	Zoro Cata Valtaga Drain Current	V <sub>DS</sub> = 250 V, V <sub>GS</sub> = 0 V			10	μΑ
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 200 V, T <sub>C</sub> = 125°C			100	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V			-100	nA
On Cha	aracteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 7.0 A		0.22	0.28	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 7.0 A		11.7		S
C <sub>iss</sub>	ic Characteristics Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,		1250	1600	pF
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,				'
C <sub>iss</sub>		$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		1250 150 30	1600 195 40	pF pF
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	20		150	195	pF
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance ing Characteristics	f = 1.0 MHz		150	195	pF pF
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub> Switchi	Input Capacitance Output Capacitance Reverse Transfer Capacitance	f = 1.0 MHz V <sub>DD</sub> = 125 V, I <sub>D</sub> = 14 A,		150 30	195 40	pF
$C_{iss}$ $C_{oss}$ $C_{rss}$ Switchi $t_{d(on)}$ $t_r$	Input Capacitance Output Capacitance Reverse Transfer Capacitance  ing Characteristics Turn-On Delay Time	f = 1.0 MHz		150 30 20	195 40 50	pF pF
$C_{iss}$ $C_{oss}$ $C_{rss}$ Switchi $t_{d(on)}$ $t_r$ $t_{d(off)}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance  ing Characteristics Turn-On Delay Time Turn-On Rise Time	f = 1.0 MHz V <sub>DD</sub> = 125 V, I <sub>D</sub> = 14 A,		150 30 20 115	195 40 50 240	pF pF
$C_{iss}$ $C_{oss}$ $C_{rss}$ Switchi $t_{d(on)}$ $t_r$ $t_{d(off)}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance  ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time	$f$ = 1.0 MHz $V_{DD}$ = 125 V, $I_{D}$ = 14 A, $R_{G}$ = 25 $\Omega$ (Note 4)	  	150 30 20 115 150	195 40 50 240 310	pF pF ns ns
$\begin{aligned} & C_{iss} \\ & C_{oss} \\ & C_{rss} \end{aligned}$ $& Switchi \\ & t_{d(on)} \\ & t_{r} \\ & t_{d(off)} \\ & t_{f} \\ & Q_{g} \end{aligned}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance  ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time	$f = 1.0 \text{ MHz}$ $V_{DD} = 125 \text{ V}, \text{ I}_{D} = 14 \text{ A},$ $R_{G} = 25 \Omega$ $(\text{Note 4})$ $V_{DS} = 200 \text{ V}, \text{ I}_{D} = 14 \text{ A},$	   	150 30 20 115 150 95	195 40 50 240 310 200	pF pF ns ns ns
$\begin{array}{c} C_{iss} \\ C_{oss} \\ C_{oss} \\ \end{array}$ $\begin{array}{c} C_{oss} \\ \\ Switchi \\ t_{d(on)} \\ t_{r} \\ t_{d(off)} \\ t_{f} \\ \\ C_{g} \\ \\ C_{gs} \\ \end{array}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance  ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge	$f$ = 1.0 MHz $V_{DD}$ = 125 V, $I_{D}$ = 14 A, $R_{G}$ = 25 $\Omega$ (Note 4)	  	150 30 20 115 150 95 47	195 40 50 240 310 200 60	pF pF ns ns ns ns
$\begin{array}{c} C_{iss} \\ C_{oss} \\ \end{array}$ $\begin{array}{c} C_{oss} \\ \end{array}$ $\begin{array}{c} Switchi \\ t_{d(on)} \\ t_{r} \\ t_{d(off)} \\ t_{f} \\ \\ Q_{g} \\ \\ Q_{gs} \\ \\ Q_{gd} \\ \end{array}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance  Ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge	$f = 1.0 \text{ MHz}$ $V_{DD} = 125 \text{ V}, I_D = 14 \text{ A},$ $R_G = 25 \Omega$ (Note 4) $V_{DS} = 200 \text{ V}, I_D = 14 \text{ A},$ $V_{GS} = 10 \text{ V}$ (Note 4)		150 30 20 115 150 95 47 6.2	195 40 50 240 310 200 60	pF pF
$C_{iss}$ $C_{oss}$ $C_{rss}$ Switchi $t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$ $Q_g$ $Q_{gs}$ $Q_{gd}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance  Ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge	$f = 1.0 \text{ MHz}$ $V_{DD} = 125 \text{ V}, \text{ I}_{D} = 14 \text{ A},$ $R_{G} = 25 \Omega$ $(Note 4)$ $V_{DS} = 200 \text{ V}, \text{ I}_{D} = 14 \text{ A},$ $V_{GS} = 10 \text{ V}$ $(Note 4)$ and Maximum Ratings		150 30 20 115 150 95 47 6.2	195 40 50 240 310 200 60 	pF pF ns ns ns ns
$C_{iss}$ $C_{oss}$ $C_{rss}$ Switchi $t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$ $Q_g$ $Q_{gs}$ $Q_{gd}$ Drain-S	Input Capacitance Output Capacitance Reverse Transfer Capacitance  Ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge	$f = 1.0 \text{ MHz}$ $V_{DD} = 125 \text{ V}, \text{ I}_{D} = 14 \text{ A},$ $R_{G} = 25 \Omega$ $(Note 4)$ $V_{DS} = 200 \text{ V}, \text{ I}_{D} = 14 \text{ A},$ $V_{GS} = 10 \text{ V}$ $(Note 4)$ $Note 4$ $Note 4$ $Note 4$ $Note 4$ $Note 5$ $Note 6$ $Note 6$ $Note 6$ $Note 7$		150 30 20 115 150 95 47 6.2 23	195 40 50 240 310 200 60	ns ns ns ns nc nC
$C_{iss}$ $C_{oss}$ $C_{oss}$ Switchi $t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$ $C_{gg}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance  Ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge  Source Diode Characteristics ar Maximum Continuous Drain-Source Diode F	$f$ = 1.0 MHz $V_{DD}$ = 125 V, $I_{D}$ = 14 A, $R_{G}$ = 25 $\Omega$ (Note 4) $V_{DS}$ = 200 V, $I_{D}$ = 14 A, $V_{GS}$ = 10 V (Note 4) $V_{CS}$ = 10 V (Note 4) $V_{CS}$ = 10 V (Note 4)		150 30 20 115 150 95 47 6.2 23	195 40 50 240 310 200 60 	pF pF ns ns ns nc nC
$C_{iss}$ $C_{oss}$ $C_{rss}$ Switchi $t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$ $Q_g$ $Q_{gs}$ $Q_{gd}$ Drain-S	Input Capacitance Output Capacitance Reverse Transfer Capacitance  ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge  Source Diode Characteristics and Maximum Continuous Drain-Source Diode	$f = 1.0 \text{ MHz}$ $V_{DD} = 125 \text{ V}, \text{ I}_{D} = 14 \text{ A},$ $R_{G} = 25 \Omega$ $(Note 4)$ $V_{DS} = 200 \text{ V}, \text{ I}_{D} = 14 \text{ A},$ $V_{GS} = 10 \text{ V}$ $(Note 4)$ $Note 4$ $Note 4$ $Note 4$ $Note 4$ $Note 5$ $Note 6$ $Note 6$ $Note 6$ $Note 7$		150 30 20 115 150 95 47 6.2 23	195 40 50 240 310 200 60  	pF pF ns ns ns ns nc nC nC

**Notes:**1. Repetitive rating : pulse-width limited by maximum junction temperature. 2. L = 3.9 mH,  $I_{AS}$  = 14 A,  $V_{DD}$  = 50 V,  $R_{G}$  = 25  $\Omega$ , starting  $T_{J}$  = 25°C. 3.  $I_{SD} \leq$  14 A, di/dt  $\leq$  300 A/µs,  $V_{DD} \leq$  BV<sub>DSS</sub>, starting  $T_{J}$  = 25°C. 4. Essentially independent of operating temperature.

# **Typical Characteristics**

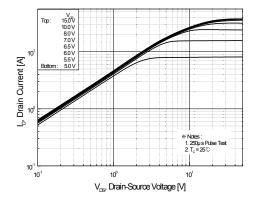


Figure 1. On-Region Characteristics

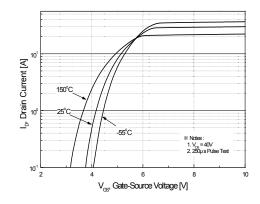


Figure 2. Transfer Characteristics

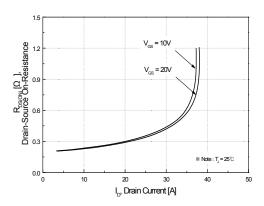


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

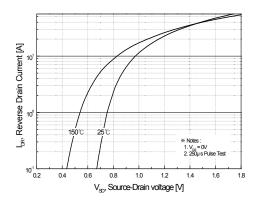


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

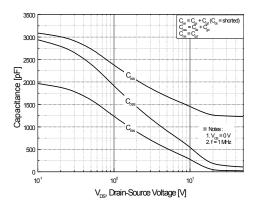


Figure 5. Capacitance Characteristics

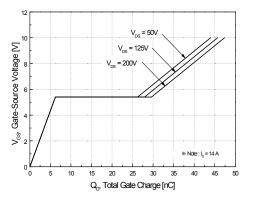


Figure 6. Gate Charge Characteristics

# Typical Characteristics (Continued)

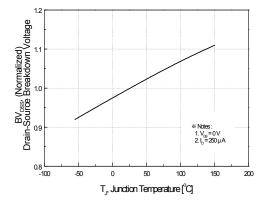


Figure 7. Breakdown Voltage Variation vs Temperature

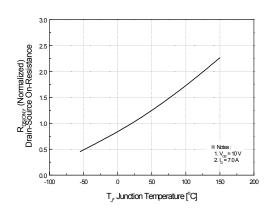


Figure 8. On-Resistance Variation vs Temperature

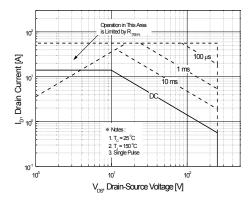


Figure 9. Maximum Safe Operating Area

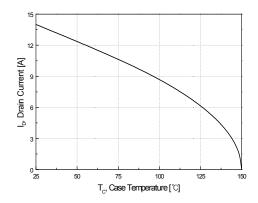


Figure 10. Maximum Drain Current vs Case Temperature

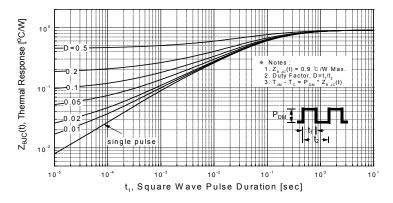


Figure 11. Transient Thermal Response Curve

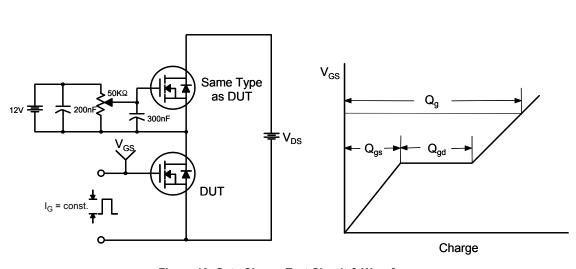


Figure 12. Gate Charge Test Circuit & Waveform

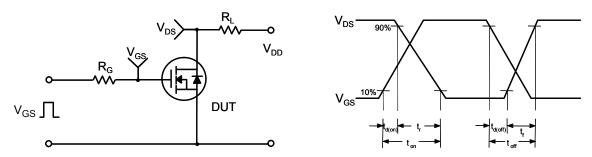


Figure 13. Resistive Switching Test Circuit & Waveforms

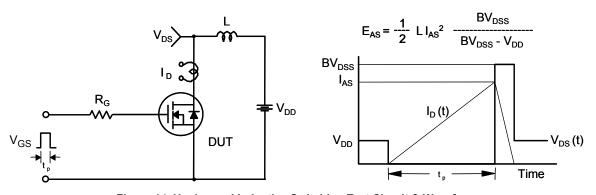
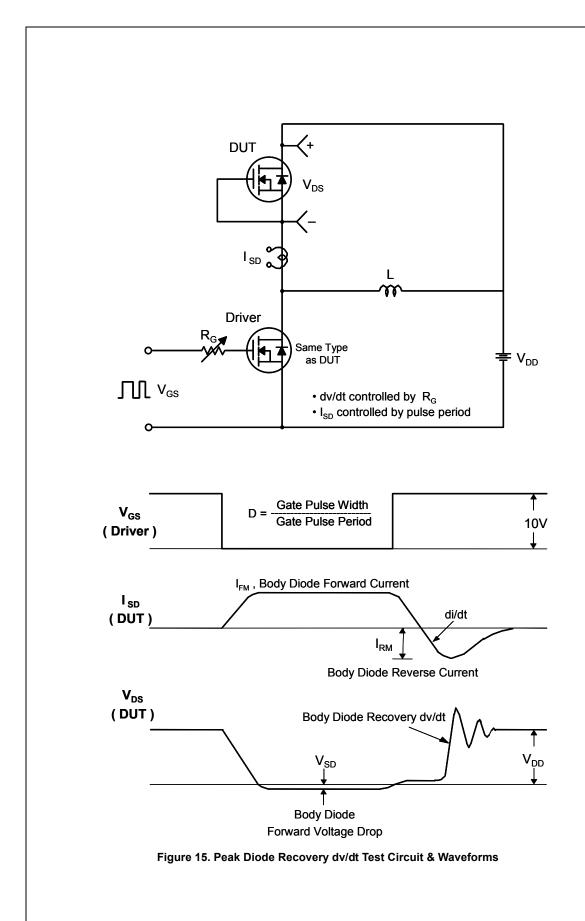
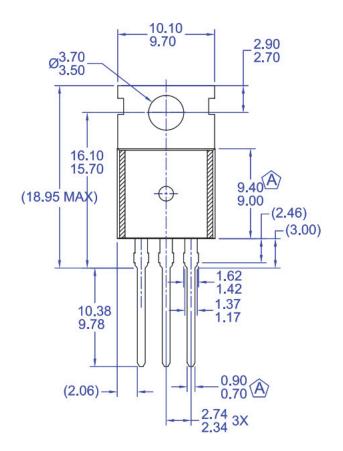
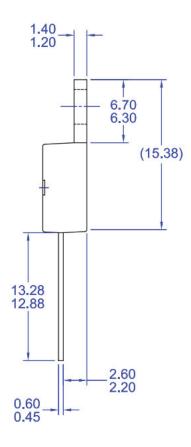


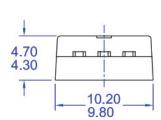
Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



### **Mechanical Dimensions**







### NOTES:

- (A) CONFORMS TO JEDEC TO-220 VARIATION AB EXCEPT WHERE NOTED
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D) DRAWING FILE/REVISION: MKT-TO220Y03REV1

Figure 16. TO220, Molded, 3-Lead, Jedec Variation AB

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